

# LUCKI CM ELECTRONICS Co.,Ltd

## APPROVAL SHEET

Customer : \_\_\_\_\_  
Part Number: 3215 Seam Sealing Crystal  
LK Part No.: L318SK32ML  
Holder : SMD3215  
Frequency: 32.768kHz  $\pm 20 \times 10^{-6}$  / 12.5PF  
Manufacturer: Lucki Electronics  
Date: 2023-04-12

| Prepared  | Checked       | Approved  |
|-----------|---------------|-----------|
| Zhao Qian | Zhang Dongwei | Zhang Bin |

(For Customer Use)

| Acceptable |  |
|------------|--|
|            |  |

## INTRODUCTION

1. The contents is subject to change without notice.  
Please exchange the specification sheets regarding the product's warranty.
2. This sheet is not intended to guarantee or provide an approval of implementation of industrial patents.
3. We have prepared this sheet as carefully as possible.  
If you find it incomplete or unsatisfactory in any respect, We would welcome your comments.

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[ 1 ] Absolute maximum ratings

| Item                | Symbol | Rating value    |
|---------------------|--------|-----------------|
| Storage temperature | TSTG   | -55°C to +125°C |
| Maximum drive level | DL     | 1.0 μW          |

[ 2 ] Operating range

| Item                        | Symbol | Value       |        |        |
|-----------------------------|--------|-------------|--------|--------|
|                             |        | Min.        | Typ.   | Max.   |
| Operating temperature range | TOPR   | -40°C       |        | +85°C  |
| Drive level                 | DL     | 0.01 μW     | 0.1 μW | 0.5 μW |
| Vibration mode              |        | Fundamental |        |        |

[ 3 ] Static characteristics

| Item                    | Symbol       | Value   | Note  |
|-------------------------|--------------|---|---|
| Frequency               | fi           | 32.768 kHz                                    |   |
| Frequency tolerance     | $\Delta f/f$ | $\pm 20 \times 10^{-6}$                       | CL = 12.5 pF<br>Ta = +25 ± 3°C, Drive level : 0.1 μW<br>Not include aging       |
| Series resistance       | Ri           | 70 kΩ Max.                                    | CI meter : Saunders 140B<br>Drive level : 0.5 μW                                |
| Motional capacitance    | Ci           | Typ. 3.4 fF                                   |   |
| Shunt capacitance       | Co           | Typ. 1.2 pF                                   |   |
| Turnover temperature    | $\theta T$   | +25 ± 5 °C                                    | Values are calculated by the frequencies at +10, +25, +40°C with C-MOS circuit. |
| Temperature coefficient | a            | $-4.0 \times 10^{-8} / ^\circ\text{C}^2$ Max. |   |
| Isolation resistance    | IR           | 500 MΩ Min.                                   | DC 100V, 60 seconds<br>Between terminal #1 and terminal #2                      |
| Aging                   | fa           | $\pm 3 \times 10^{-6}$ / year                 | Ta = +25 °C ± 3 °C<br>Drive level : 0.1 μW                                      |

#### [ 4 ] Environmental and Mechanical characteristics

| No. | Items                         | Value                                     | Conditions  |
|-----|-------------------------------|---|---|
| 1   | Shock resistance              | *3Δ f/f : ± 8 × 10 <sup>-6</sup>          | 100g dummy(SEIKO EPSON Standard), Natural drop from 1500 mm height on to the concrete.<br>3 directions × 10 times *2  |
| 2   | Vibration resistance          | *3Δ f/f : ± 3 × 10 <sup>-6</sup>          | 10 Hz to 55 Hz amplitude 0.75 mm<br>55 Hz to 500 Hz acceleration 98 m/s <sup>2</sup><br>10 Hz → 500 Hz → 10 Hz 15 min./cycle<br>6 h (2 hours , 3 directions) *2 |
| 3   | Soldering heat resistance     | Δ f/f : ± 5 × 10 <sup>-6</sup>            | For convention reflow soldering furnace (2 times)   |
| 4   | High temperature storage      | *3Δ f/f : ± 10 × 10 <sup>-6</sup>         | +125 °C × 1000 h *1   |
|     |                               | *3Δ f/f : ± 7 × 10 <sup>-6</sup>          | +85°C× 1000 h *1  |
| 5   | Low temperature storage       | *3Δ f/f : ± 10 × 10 <sup>-6</sup>         | -55 °C× 1000 h *1   |
| 6   | High temperature and humidity | *3Δ f/f : ± 10 × 10 <sup>-6</sup>         | +85°C × 85%RH × 1000 h *1   |
| 7   | Temperature cycle             | *3Δ f/f : ± 10 × 10 <sup>-6</sup>         | -55 °C ↔ +125°C<br>30 minutes at each temperature × 100 cycles *1   |
| 8   | Sealing                       | *3<br>1 × 10 <sup>-8</sup> hPa·l / s Max. | For He leak detector  |
| 9   | Shear                         | No peeling-off at a soldered part         | 20 N press for 10 ± 1 s.<br>Ref. IEC 60068-2-21   |
| 10  | Pull - off                    | No peeling-off at a soldered part         | 20 N press for 10 ± 1 s.<br>Ref. IEC 60068-2-21   |
| 11  | Substrate bending             | No peeling-off at a soldered part         | Bend width reaches 3 mm and hold for 5 s ± 1 s × 1 time Ref. IEC 60068-2-21   |
| 12  | Solvent resistance            | The marking shall be legible              | Ref. JIS C 0052 or IEC 60068-2-45   |

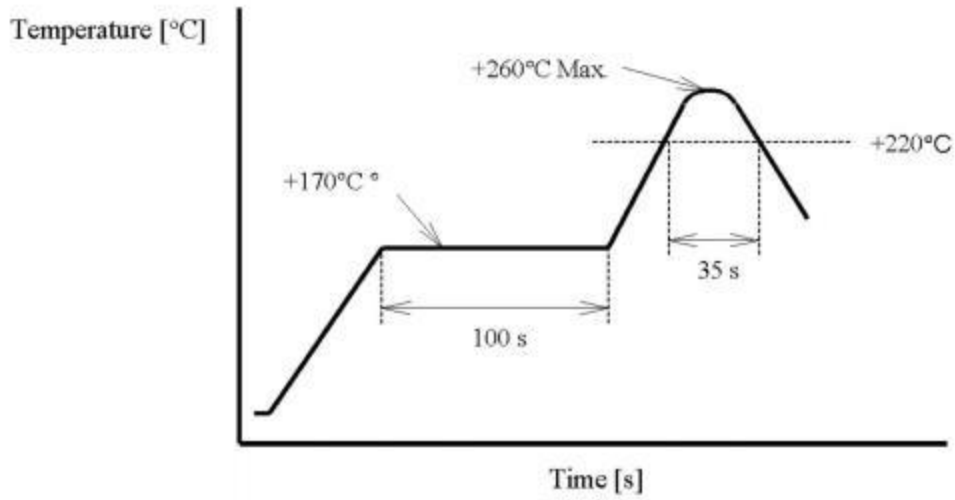
#### < Notes >

- \*1 Each test done independently.
- \*2 Measuring 2 h to 24 h later leaving in room temperature after each test. Drive level : 0.5 μW
- \*3 Pre conditionings( Treat the Reflow 2 times with the following profile) Initial value shall be after 24 h at room temperature.  
Shift of series resistance at before and after the test should be less than ±20 % or less than ±15kΩ.  
In case high temperature storage(+125°C × 1 000 h), Soldering heat resistance, shift of series resistance at before and after the test should be less than ±30 % or ±20 kΩ.

◆ Air reflow

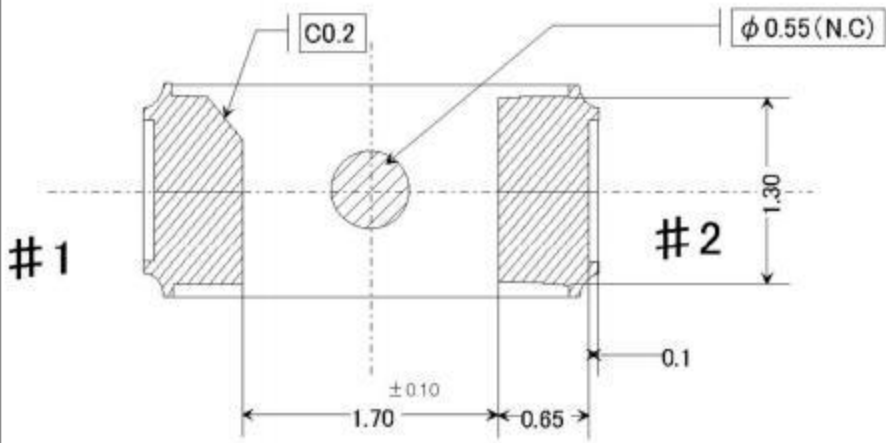
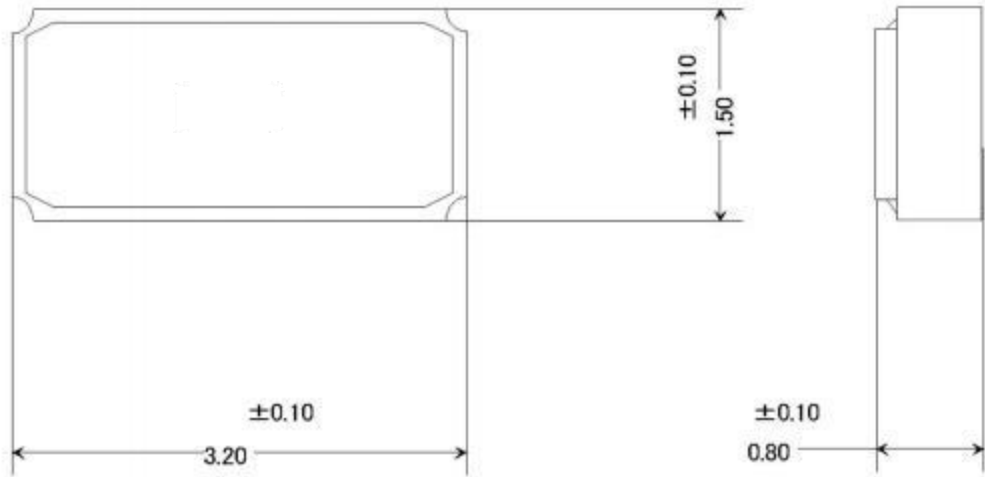
Pre heating temperature: +170 [°C]  
Heating temperature : +220 [°C]

Pre heating time: 100 [s]  
Heating time : 30 [s]



[ 5 ] Dimensions and Marking layout

1. Dimensions



Package : Ceramic( $Al_2O_3$ )  
 Terminal Au plate : 0.5  $\mu m$  Min.  
 Lid : Glass

2. Internal Connection

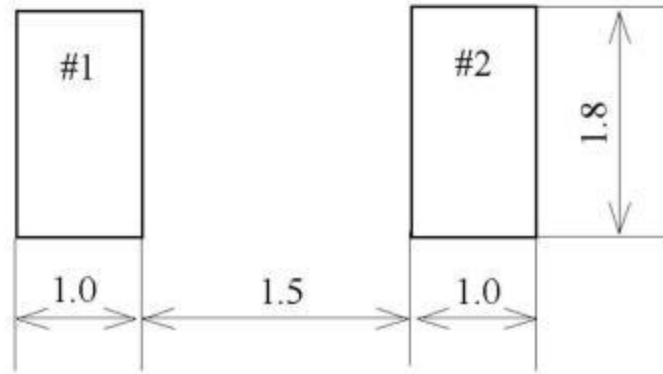


#1                      #2

|      |        |                    |            |      |          |
|------|--------|--------------------|------------|------|----------|
| Type | FC-135 | Terminal treatment | Au plating | Unit | 1 = 1 mm |
|------|--------|--------------------|------------|------|----------|

3. Recommended soldering pattern

Unit : 1 = 1 mm



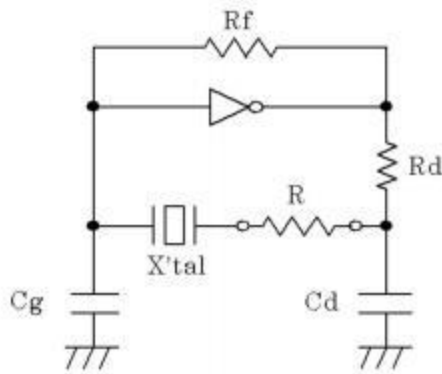
|      |        |      |        |
|------|--------|------|--------|
| Type | FC-135 | Unit | 1=1 mm |
|------|--------|------|--------|



## [ 6 ] Notes

1. Max two (2) times reflow is allowed. Once miss soldering is happened, hand work soldering by soldering iron is recommended. (+350°C × within 5 s)
2. Patterning should be followed by our recommended one.
3. Applying excessive excitation force to the crystal resonator may cause deterioration damage.
4. Unless adequate negative resistance is allocated in the oscillation circuit, start up time of oscillation may be increased, or no oscillation may occur.

How to check the negative resistance.



- (1) Connect the resistance (R) to the circuit in series with the crystal resonator.
- (2) Adjust R so that oscillation can start (or stop).
- (3) Measure R when oscillation just start (or stop) in above (2).
- (4) Get the negative resistance  
 $-R = R + CI$  value.
- (5) Recommended -R  
 $|-R| > CI \times (5 \sim 10)$

5. The shortest patterning line on board is recommendable.  
Too long line on board may cause of abnormal oscillation.
6. To avoid mull function, no pattern under or near the crystal is allowed.  
Solder paste should be more than 150 μm thickness.
7. This device must be stored at the normal temperature and humidity conditions before mounting on a board.
8. Too much exciting shock or vibration may cause deterioration on damage.  
Depending on the condition such as a shock in assembly machinery, the products may be damaged.  
Please check your condition in advance to maintain shock level to be smallest.
9. Depending on the conditions, ultrasonic cleaning may cause resonant damage of the internal crystal resonator. Since we are unable to determine the conditions (type of cleaning unit, power, time, conditions inside the bath, etc.) to be used in your company, we cannot guarantee the safety of this unit when it is cleaned in an ultrasonic cleaner.
10. Ink marking may be damaged by some kind of solvent, please take precautions when choosing solvent by your selves.
11. Please refer to packing specification regarding how to storage the products in the pack.